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# **PIC18FXX8**

## **Data Sheet**

28/40-Pin High-Performance,  
Enhanced Flash Microcontrollers  
with CAN Module

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## 28/40-Pin High-Performance, Enhanced Flash Microcontrollers with CAN

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### High-Performance RISC CPU:

- Linear program memory addressing up to 2 Mbytes
- Linear data memory addressing to 4 Kbytes
- Up to 10 MIPS operation
- DC – 40 MHz clock input
- 4 MHz-10 MHz oscillator/clock input with PLL active
- 16-bit wide instructions, 8-bit wide data path
- Priority levels for interrupts
- 8 x 8 Single-Cycle Hardware Multiplier

### Peripheral Features:

- High current sink/source 25 mA/25 mA
- Three external interrupt pins
- Timer0 module: 8-bit/16-bit timer/counter with 8-bit programmable prescaler
- Timer1 module: 16-bit timer/counter
- Timer2 module: 8-bit timer/counter with 8-bit period register (time base for PWM)
- Timer3 module: 16-bit timer/counter
- Secondary oscillator clock option – Timer1/Timer3
- Capture/Compare/PWM (CCP) modules; CCP pins can be configured as:
  - Capture input: 16-bit, max resolution 6.25 ns
  - Compare: 16-bit, max resolution 100 ns (TCY)
  - PWM output: PWM resolution is 1 to 10-bit  
Max. PWM freq. @ :8-bit resolution = 156 kHz  
10-bit resolution = 39 kHz
- Enhanced CCP module which has all the features of the standard CCP module, but also has the following features for advanced motor control:
  - 1, 2 or 4 PWM outputs
  - Selectable PWM polarity
  - Programmable PWM dead time
- Master Synchronous Serial Port (MSSP) with two modes of operation:
  - 3-wire SPI™ (Supports all 4 SPI modes)
  - I<sup>2</sup>C™ Master and Slave mode
- Addressable USART module:
  - Supports interrupt-on-address bit

### Advanced Analog Features:

- 10-bit, up to 8-channel Analog-to-Digital Converter module (A/D) with:
  - Conversion available during Sleep
  - Up to 8 channels available
- Analog Comparator module:
  - Programmable input and output multiplexing
- Comparator Voltage Reference module
- Programmable Low-Voltage Detection (LVD) module:
  - Supports interrupt-on-Low-Voltage Detection
- Programmable Brown-out Reset (BOR)

### CAN bus Module Features:

- Complies with ISO CAN Conformance Test
- Message bit rates up to 1 Mbps
- Conforms to CAN 2.0B Active Spec with:
  - 29-bit Identifier Fields
  - 8-byte message length
  - 3 Transmit Message Buffers with prioritization
  - 2 Receive Message Buffers
  - 6 full, 29-bit Acceptance Filters
  - Prioritization of Acceptance Filters
  - Multiple Receive Buffers for High Priority Messages to prevent loss due to overflow
  - Advanced Error Management Features

### Special Microcontroller Features:

- Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own on-chip RC oscillator
- Programmable code protection
- Power-saving Sleep mode
- Selectable oscillator options, including:
  - 4x Phase Lock Loop (PLL) of primary oscillator
  - Secondary Oscillator (32 kHz) clock input
- In-Circuit Serial Programming™ (ICSP™) via two pins

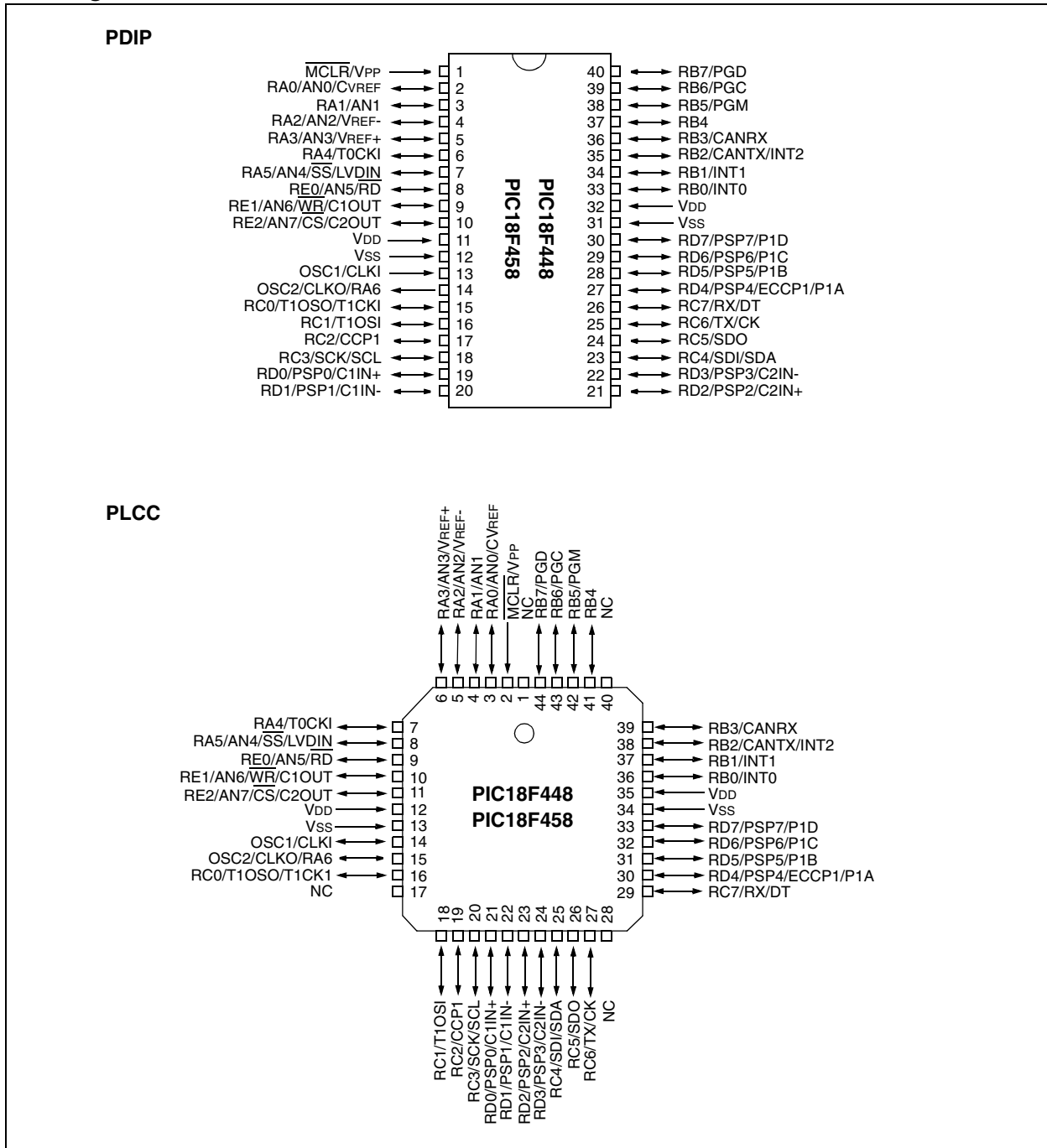
### Flash Technology:

- Low-power, high-speed Enhanced Flash technology
- Fully static design
- Wide operating voltage range (2.0V to 5.5V)
- Industrial and Extended temperature ranges

# PIC18FXX8

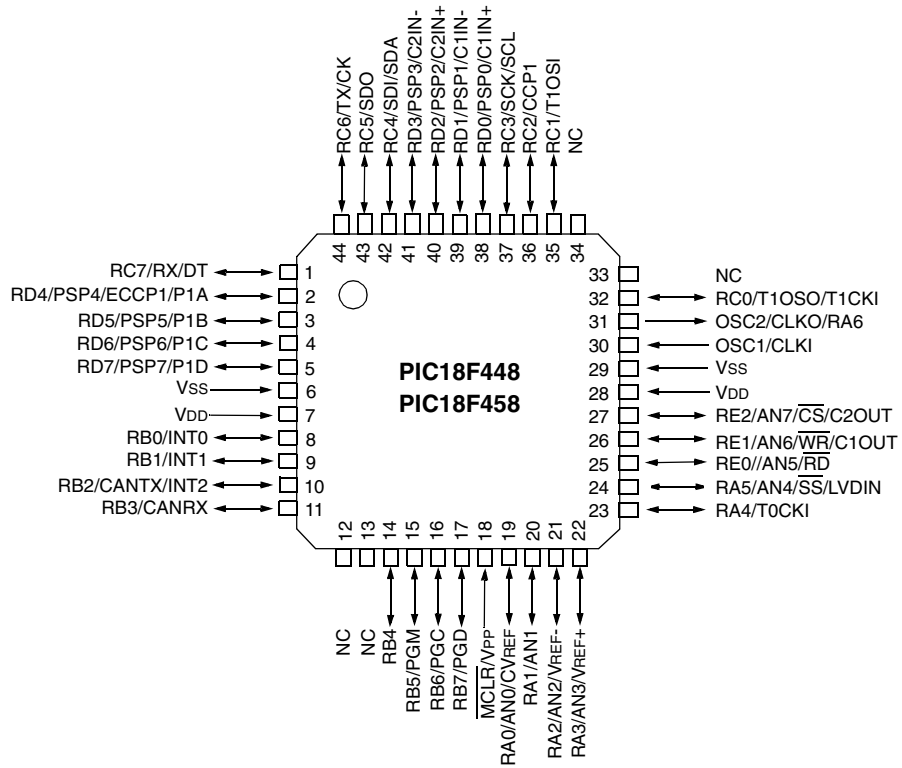
Device	Program Memory		Data Memory		I/O	10-bit A/D (ch)	Comparators	CCP/ ECCP (PWM)	MSSP		USART	Timers 8/16-bit
	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)					SPI™	Master I <sup>2</sup> C™		
PIC18F248	16K	8192	768	256	22	5	—	1/0	Y	Y	Y	1/3
PIC18F258	32K	16384	1536	256	22	5	—	1/0	Y	Y	Y	1/3
PIC18F448	16K	8192	768	256	33	8	2	1/1	Y	Y	Y	1/3
PIC18F458	32K	16384	1536	256	33	8	2	1/1	Y	Y	Y	1/3

## Pin Diagrams

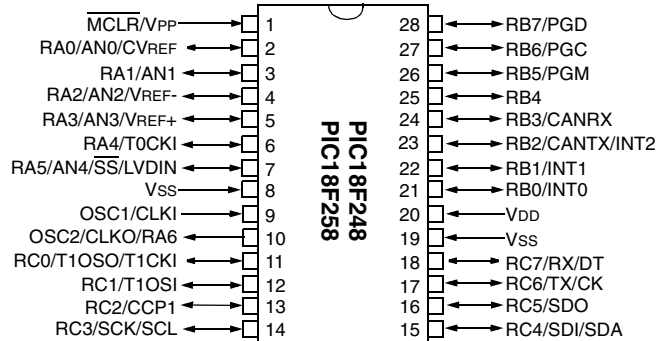


## Pin Diagrams (Continued)

### TQFP



### SPDIP, SOIC



# PIC18FXX8

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# PIC18FXX8

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NOTES:

## 1.0 DEVICE OVERVIEW

This document contains device specific information for the following devices:

- PIC18F248
- PIC18F258
- PIC18F448
- PIC18F458

These devices are available in 28-pin, 40-pin and 44-pin packages. They are differentiated from each other in four ways:

1. PIC18FX58 devices have twice the Flash program memory and data RAM of PIC18FX48 devices (32 Kbytes and 1536 bytes vs. 16 Kbytes and 768 bytes, respectively).

2. PIC18F2X8 devices implement 5 A/D channels, as opposed to 8 for PIC18F4X8 devices.
3. PIC18F2X8 devices implement 3 I/O ports, while PIC18F4X8 devices implement 5.
4. Only PIC18F4X8 devices implement the Enhanced CCP module, analog comparators and the Parallel Slave Port.

All other features for devices in the PIC18FXX8 family, including the serial communications modules, are identical. These are summarized in Table 1-1.

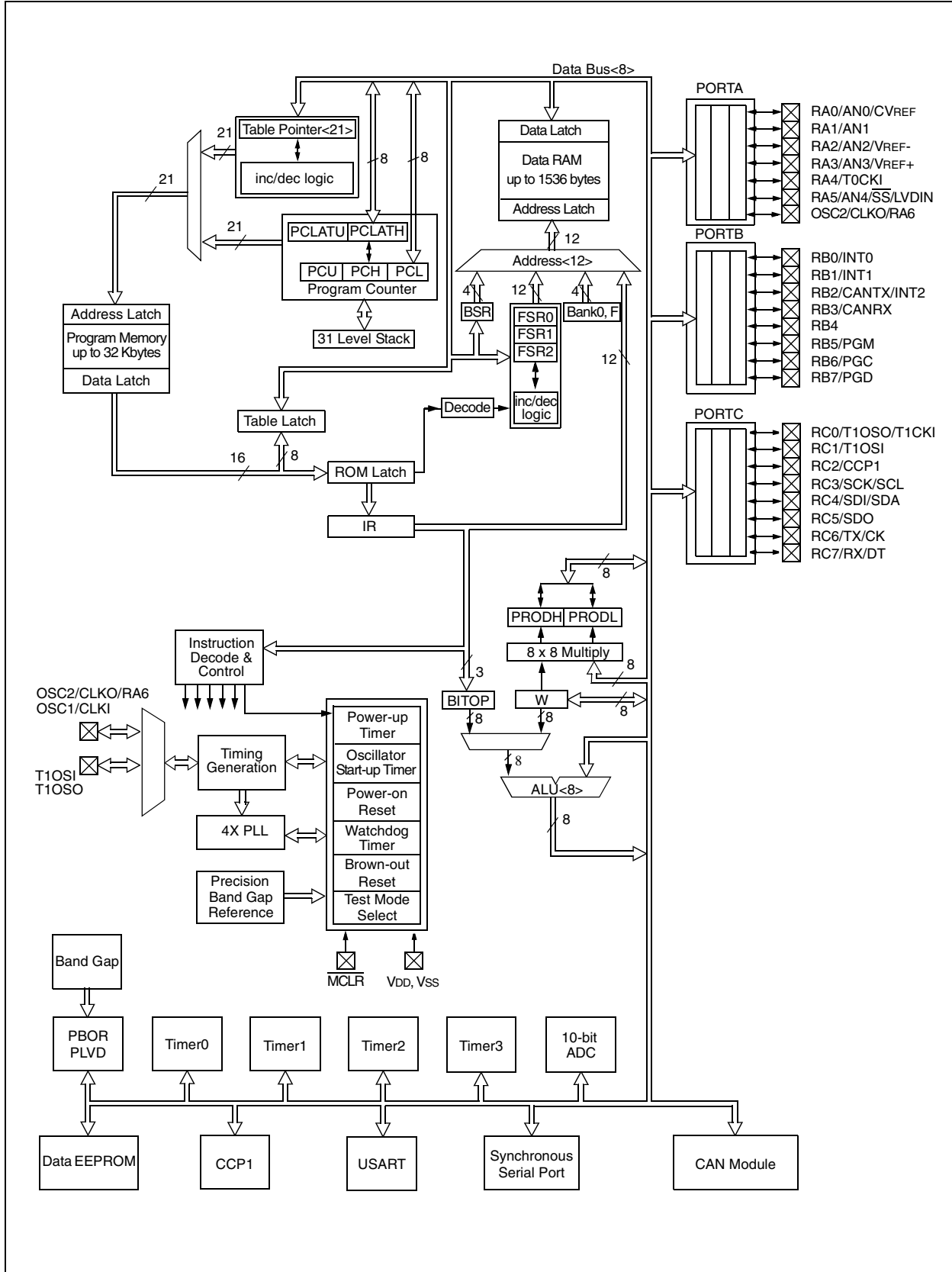
Block diagrams of the PIC18F2X8 and PIC18F4X8 devices are provided in Figure 1-1 and Figure 1-2, respectively. The pinouts for these device families are listed in Table 1-2.

**TABLE 1-1: PIC18FXX8 DEVICE FEATURES**

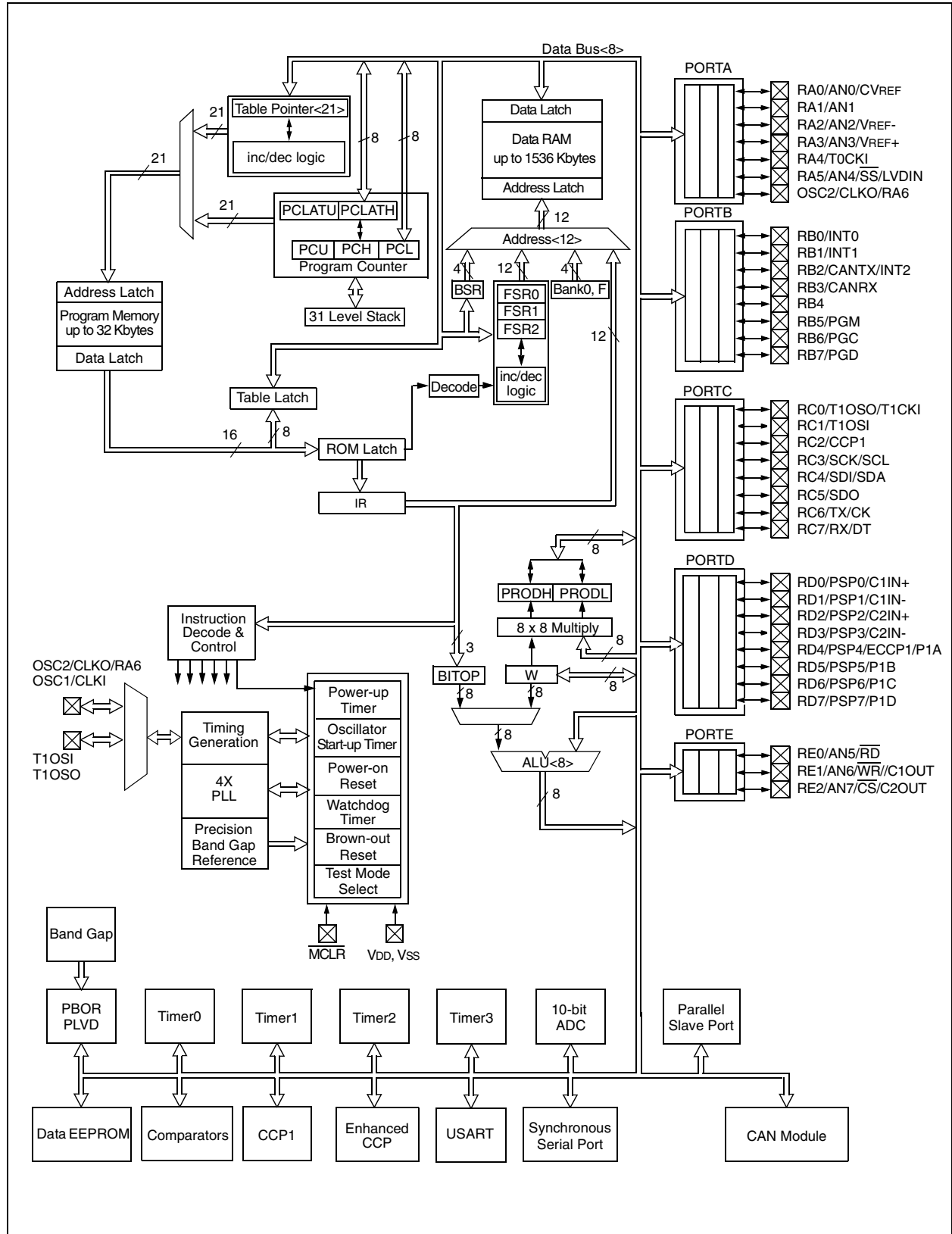
Features		PIC18F248	PIC18F258	PIC18F448	PIC18F458
Operating Frequency		DC – 40 MHz	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz
Internal Program Memory	Bytes	16K	32K	16K	32K
	# of Single-Word Instructions	8192	16384	8192	16384
Data Memory (Bytes)		768	1536	768	1536
Data EEPROM Memory (Bytes)		256	256	256	256
Interrupt Sources		17	17	21	21
I/O Ports		Ports A, B, C	Ports A, B, C	Ports A, B, C, D, E	Ports A, B, C, D, E
Timers		4	4	4	4
Capture/Compare/PWM Modules		1	1	1	1
Enhanced Capture/Compare/PWM Modules		—	—	1	1
Serial Communications		MSSP, CAN, Addressable USART	MSSP, CAN, Addressable USART	MSSP, CAN, Addressable USART	MSSP, CAN, Addressable USART
Parallel Communications (PSP)		No	No	Yes	Yes
10-bit Analog-to-Digital Converter		5 input channels	5 input channels	8 input channels	8 input channels
Analog Comparators		No	No	2	2
Analog Comparators VREF Output		N/A	N/A	Yes	Yes
Resets (and Delays)		POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST)
Programmable Low-Voltage Detect		Yes	Yes	Yes	Yes
Programmable Brown-out Reset		Yes	Yes	Yes	Yes
CAN Module		Yes	Yes	Yes	Yes
In-Circuit Serial Programming™ (ICSP™)		Yes	Yes	Yes	Yes
Instruction Set		75 Instructions	75 Instructions	75 Instructions	75 Instructions
Packages		28-pin SPDIP 28-pin SOIC	28-pin SPDIP 28-pin SOIC	40-pin PDIP 44-pin PLCC 44-pin TQFP	40-pin PDIP 44-pin PLCC 44-pin TQFP

# PIC18FXX8

FIGURE 1-1: PIC18F248/258 BLOCK DIAGRAM



**FIGURE 1-2: PIC18F448/458 BLOCK DIAGRAM**



# PIC18FXX8

**TABLE 1-2: PIC18FXX8 PINOUT I/O DESCRIPTIONS**

Pin Name	Pin Number				Pin Type	Buffer Type	Description
	PIC18F248/258	PIC18F448/458					
	SPDIP, SOIC	PDIP	TQFP	PLCC			
MCLR/VPP  MCLR  VPP	1	1	18	2	I  P	ST  —	Master Clear (input) or programming voltage (output). Master Clear (Reset) input. This pin is an active low Reset to the device. Programming voltage input.
NC	—	—	12, 13, 33, 34	1, 17, 28, 40	—	—	These pins should be left unconnected.
OSC1/CLKI  OSC1  CLKI	9	13	30	14	I  I	CMOS/ST  CMOS	Oscillator crystal or external clock input. Oscillator crystal input or external clock source input. ST buffer when configured in RC mode; otherwise, CMOS. External clock source input. Always associated with pin function OSC1 (see OSC1/CLKI, OSC2/CLKO pins).
OSC2/CLKO/RA6 OSC2  CLKO  RA6	10	14	31	15	O  O  I/O	—  —  TTL	Oscillator crystal or clock output. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate. General purpose I/O pin.

**Legend:** TTL = TTL compatible input  
 ST = Schmitt Trigger input with CMOS levels  
 I = Input  
 P = Power  
 CMOS = CMOS compatible input or output  
 Analog = Analog input  
 O = Output  
 OD = Open-Drain (no P diode to VDD)

**TABLE 1-2: PIC18FXX8 PINOUT I/O DESCRIPTIONS (CONTINUED)**

Pin Name	Pin Number				Pin Type	Buffer Type	Description
	PIC18F248/258	PIC18F448/458					
	SPDIP, SOIC	PDIP	TQFP	PLCC			
RA0/AN0/CVREF RA0 AN0 CVREF	2	2	19	3	I/O I O	TTL Analog Analog	PORTA is a bidirectional I/O port.  Digital I/O. Analog input 0. Comparator voltage reference output.
RA1/AN1 RA1 AN1	3	3	20	4	I/O I	TTL Analog	Digital I/O. Analog input 1.
RA2/AN2/VREF- RA2 AN2 VREF-	4	4	21	5	I/O I I	TTL Analog Analog	Digital I/O. Analog input 2. A/D reference voltage (Low) input.
RA3/AN3/VREF+ RA3 AN3 VREF+	5	5	22	6	I/O I I	TTL Analog Analog	Digital I/O. Analog input 3. A/D reference voltage (High) input.
RA4/T0CKI RA4  T0CKI	6	6	23	7	I/O  I	TTL/OD  ST	Digital I/O – open-drain when configured as output. Timer0 external clock input.
RA5/AN4/ $\overline{SS}$ /LVDIN RA5 AN4 $\overline{SS}$ LVDIN	7	7	24	8	I/O I I I	TTL Analog ST Analog	Digital I/O. Analog input 4. SPI™ slave select input. Low-Voltage Detect input.
RA6							See the OSC2/CLKO/RA6 pin.

**Legend:** TTL = TTL compatible input  
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 OD = Open-Drain (no P diode to VDD)

# PIC18FXX8

**TABLE 1-2: PIC18FXX8 PINOUT I/O DESCRIPTIONS (CONTINUED)**

Pin Name	Pin Number				Pin Type	Buffer Type	Description
	PIC18F248/258	PIC18F448/458					
	SPDIP, SOIC	PDIP	TQFP	PLCC			
RB0/INT0 RB0 INT0	21	33	8	36	I/O I	TTL ST	PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.  Digital I/O. External interrupt 0.
RB1/INT1 RB1 INT1	22	34	9	37	I/O I	TTL ST	Digital I/O. External interrupt 1.
RB2/CANTX/INT2 RB2 CANTX INT2	23	35	10	38	I/O O I	TTL TTL ST	Digital I/O. Transmit signal for CAN bus. External interrupt 2.
RB3/CANRX RB3 CANRX	24	36	11	39	I/O I	TTL TTL	Digital I/O. Receive signal for CAN bus.
RB4	25	37	14	41	I/O	TTL	Digital I/O. Interrupt-on-change pin.
RB5/PGM RB5  PGM	26	38	15	42	I/O  I	TTL  ST	Digital I/O. Interrupt-on-change pin. Low-voltage ICSP™ programming enable.
RB6/PGC RB6  PGC	27	39	16	43	I/O  I	TTL  ST	Digital I/O. In-Circuit Debugger pin. Interrupt-on-change pin. ICSP programming clock.
RB7/PGD RB7  PGD	28	40	17	44	I/O  I/O	TTL  ST	Digital I/O. In-Circuit Debugger pin. Interrupt-on-change pin. ICSP programming data.

**Legend:** TTL = TTL compatible input  
 ST = Schmitt Trigger input with CMOS levels  
 I = Input  
 P = Power  
 CMOS = CMOS compatible input or output  
 Analog = Analog input  
 O = Output  
 OD = Open-Drain (no P diode to VDD)



**TABLE 1-2: PIC18FXX8 PINOUT I/O DESCRIPTIONS (CONTINUED)**

Pin Name	Pin Number				Pin Type	Buffer Type	Description
	PIC18F248/258	PIC18F448/458					
	SPDIP, SOIC	PDIP	TQFP	PLCC			
RC0/T1OSO/T1CKI RC0 T1OSO T1CKI	11	15	32	16	I/O O I	ST — ST	PORTC is a bidirectional I/O port.  Digital I/O. Timer1 oscillator output. Timer1/Timer3 external clock input.
RC1/T1OSI RC1 T1OSI	12	16	35	18	I/O I	ST CMOS	Digital I/O. Timer1 oscillator input.
RC2/CCP1 RC2 CCP1	13	17	36	19	I/O I/O	ST ST	Digital I/O. Capture 1 input/Compare 1 output/PWM1 output.
RC3/SCK/SCL RC3 SCK  SCL	14	18	37	20	I/O I/O  I/O	ST ST  ST	Digital I/O. Synchronous serial clock input/output for SPI™ mode. Synchronous serial clock input/output for I <sup>2</sup> C™ mode.
RC4/SDI/SDA RC4 SDI SDA	15	23	42	25	I/O I I/O	ST ST ST	Digital I/O. SPI data in. I <sup>2</sup> C data I/O.
RC5/SDO RC5 SDO	16	24	43	26	I/O O	ST —	Digital I/O. SPI data out.
RC6/TX/CK RC6 TX  CK	17	25	44	27	I/O O  I/O	ST —  ST	Digital I/O. USART asynchronous transmit. USART synchronous clock (see RX/DT).
RC7/RX/DT RC7 RX DT	18	26	1	29	I/O I I/O	ST ST ST	Digital I/O. USART asynchronous receive. USART synchronous data (see TX/CK).

**Legend:** TTL = TTL compatible input  
 ST = Schmitt Trigger input with CMOS levels  
 I = Input  
 P = Power

CMOS = CMOS compatible input or output  
 Analog = Analog input  
 O = Output  
 OD = Open-Drain (no P diode to VDD)

# PIC18FXX8

**TABLE 1-2: PIC18FXX8 PINOUT I/O DESCRIPTIONS (CONTINUED)**

Pin Name	Pin Number				Pin Type	Buffer Type	Description
	PIC18F248/258	PIC18F448/458					
	SPDIP, SOIC	PDIP	TQFP	PLCC			
RD0/PSP0/C1IN+ RD0 PSP0 C1IN+	—	19	38	21	I/O I/O I	ST TTL Analog	PORTD is a bidirectional I/O port. These pins have TTL input buffers when external memory is enabled.  Digital I/O. Parallel Slave Port data. Comparator 1 input.
RD1/PSP1/C1IN- RD1 PSP1 C1IN-	—	20	39	22	I/O I/O I	ST TTL Analog	Digital I/O. Parallel Slave Port data. Comparator 1 input.
RD2/PSP2/C2IN+ RD2 PSP2 C2IN+	—	21	40	23	I/O I/O I	ST TTL Analog	Digital I/O. Parallel Slave Port data. Comparator 2 input.
RD3/PSP3/C2IN- RD3 PSP3 C2IN-	—	22	41	24	I/O I/O I	ST TTL Analog	Digital I/O. Parallel Slave Port data. Comparator 2 input.
RD4/PSP4/ECCP1/ P1A RD4 PSP4 ECCP1 P1A	—	27	2	30	I/O I/O I/O O	ST TTL ST —	Digital I/O. Parallel Slave Port data. ECCP1 capture/compare. ECCP1 PWM output A.
RD5/PSP5/P1B RD5 PSP5 P1B	—	28	3	31	I/O I/O O	ST TTL —	Digital I/O. Parallel Slave Port data. ECCP1 PWM output B.
RD6/PSP6/P1C RD6 PSP6 P1C	—	29	4	32	I/O I/O O	ST TTL —	Digital I/O. Parallel Slave Port data. ECCP1 PWM output C.
RD7/PSP7/P1D RD7 PSP7 P1D	—	30	5	33	I/O I/O O	ST TTL —	Digital I/O. Parallel Slave Port data. ECCP1 PWM output D.

**Legend:** TTL = TTL compatible input  
 ST = Schmitt Trigger input with CMOS levels  
 I = Input  
 P = Power  
 CMOS = CMOS compatible input or output  
 Analog = Analog input  
 O = Output  
 OD = Open-Drain (no P diode to VDD)

**TABLE 1-2: PIC18FXX8 PINOUT I/O DESCRIPTIONS (CONTINUED)**

Pin Name	Pin Number				Pin Type	Buffer Type	Description
	PIC18F248/258	PIC18F448/458					
	SPDIP, SOIC	PDIP	TQFP	PLCC			
RE0/AN5/ $\overline{RD}$ RE0 AN5 $\overline{RD}$	—	8	25	9	I/O I I	ST Analog TTL	PORTC is a bidirectional I/O port.  Digital I/O. Analog input 5. Read control for Parallel Slave Port (see $\overline{WR}$ and $\overline{CS}$ pins).
RE1/AN6/ $\overline{WR}$ /C1OUT RE1 AN6 $\overline{WR}$  C1OUT	—	9	26	10	I/O I I  O	ST Analog TTL  Analog	Digital I/O. Analog input 6. Write control for Parallel Slave Port (see $\overline{CS}$ and $\overline{RD}$ pins). Comparator 1 output.
RE2/AN7/ $\overline{CS}$ /C2OUT RE2 AN7 $\overline{CS}$  C2OUT	—	10	27	11	I/O I I  O	ST Analog TTL  Analog	Digital I/O. Analog input 7. Chip select control for Parallel Slave Port (see $\overline{RD}$ and $\overline{WR}$ pins). Comparator 2 output.
Vss	19, 8	12, 31	6, 29	13, 34	—	—	Ground reference for logic and I/O pins.
VDD	20	11, 32	7, 28	12, 35	—	—	Positive supply for logic and I/O pins.

**Legend:** TTL = TTL compatible input  
 ST = Schmitt Trigger input with CMOS levels  
 I = Input  
 P = Power  
 CMOS = CMOS compatible input or output  
 Analog = Analog input  
 O = Output  
 OD = Open-Drain (no P diode to VDD)

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NOTES:

## 2.0 OSCILLATOR CONFIGURATIONS

### 2.1 Oscillator Types

The PIC18FXX8 can be operated in one of eight oscillator modes, programmable by three configuration bits (FOSC2, FOSC1 and FOSC0).

1. LP Low-Power Crystal
2. XT Crystal/Resonator
3. HS High-Speed Crystal/Resonator
4. HS4 High-Speed Crystal/Resonator with PLL enabled
5. RC External Resistor/Capacitor
6. RCIO External Resistor/Capacitor with I/O pin enabled
7. EC External Clock
8. ECIO External Clock with I/O pin enabled

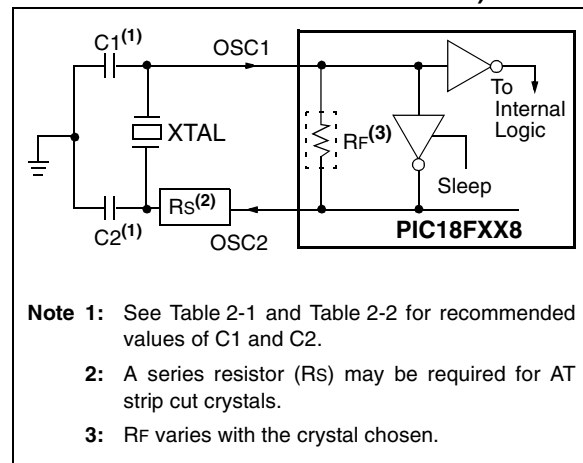
### 2.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HS4 (PLL) Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 2-1 shows the pin connections. An external clock source may also be connected to the OSC1 pin, as shown in Figure 2-3 and Figure 2-4.

The PIC18FXX8 oscillator design requires the use of a parallel cut crystal.

**Note:** Use of a series cut crystal may give a frequency out of the crystal manufacturer's specifications.

**FIGURE 2-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)**



**TABLE 2-1: CERAMIC RESONATORS**

Ranges Tested:			
Mode	Freq	OSC1	OSC2
XT	455 kHz	68-100 pF	68-100 pF
	2.0 MHz	15-68 pF	15-68 pF
	4.0 MHz	15-68 pF	15-68 pF
HS	8.0 MHz	10-68 pF	10-68 pF
	16.0 MHz	10-22 pF	10-22 pF
<b>These values are for design guidance only.</b> See notes following Table 2-2.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	±0.3%	
2.0 MHz	Murata Erie CSA2.00MG	±0.5%	
4.0 MHz	Murata Erie CSA4.00MG	±0.5%	
8.0 MHz	Murata Erie CSA8.00MT	±0.5%	
16.0 MHz	Murata Erie CSA16.00MX	±0.5%	
All resonators used did not have built-in capacitors.			

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**TABLE 2-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR**

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32.0 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1.0 MHz	15 pF	15 pF
	4.0 MHz	15 pF	15 pF
HS	4.0 MHz	15 pF	15 pF
	8.0 MHz	15-33 pF	15-33 pF
	20.0 MHz	15-33 pF	15-33 pF
	25.0 MHz	15-33 pF	15-33 pF
<b>These values are for design guidance only.</b> See notes on this page.			
<b>Crystals Used</b>			
32.0 kHz	Epson C-001R32.768K-A	±20 PPM	
200 kHz	STD XTL 200.000KHz	±20 PPM	
1.0 MHz	ECS ECS-10-13-1	±50 PPM	
4.0 MHz	ECS ECS-40-20-1	±50 PPM	
8.0 MHz	EPSON CA-301 8.000M-C	±30 PPM	
20.0 MHz	EPSON CA-301 20.000M-C	±30 PPM	

- Note 1:** Recommended values of C1 and C2 are identical to the ranges tested (Table 2-1).
- Higher capacitance increases the stability of the oscillator but also increases the start-up time.
  - Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
  - Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification.

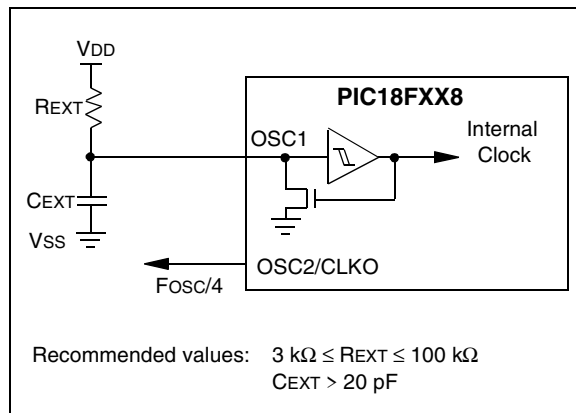
## 2.3 RC Oscillator

For timing insensitive applications, the “RC” and “RCIO” device options offer additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 2-2 shows how the RC combination is connected.

In the RC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic.

**Note:** If the oscillator frequency divided by 4 signal is not required in the application, it is recommended to use RCIO mode to save current.

**FIGURE 2-2: RC OSCILLATOR MODE**



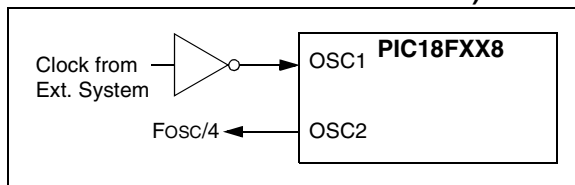
The RCIO Oscillator mode functions like the RC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6).

## 2.4 External Clock Input

The EC and ECIO Oscillator modes require an external clock source to be connected to the OSC1 pin. The feedback device between OSC1 and OSC2 is turned off in these modes to save current. There is no oscillator start-up time required after a Power-on Reset or after a recovery from Sleep mode.

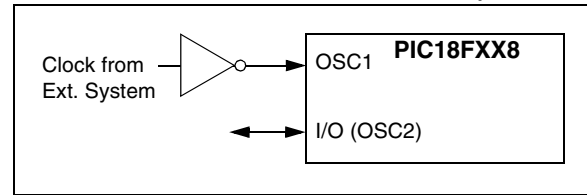
In the EC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 2-3 shows the pin connections for the EC Oscillator mode.

**FIGURE 2-3: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)**



The ECIO Oscillator mode functions like the EC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. Figure 2-4 shows the pin connections for the ECIO Oscillator mode.

**FIGURE 2-4: EXTERNAL CLOCK INPUT OPERATION (ECIO CONFIGURATION)**



## 2.5 HS4 (PLL)

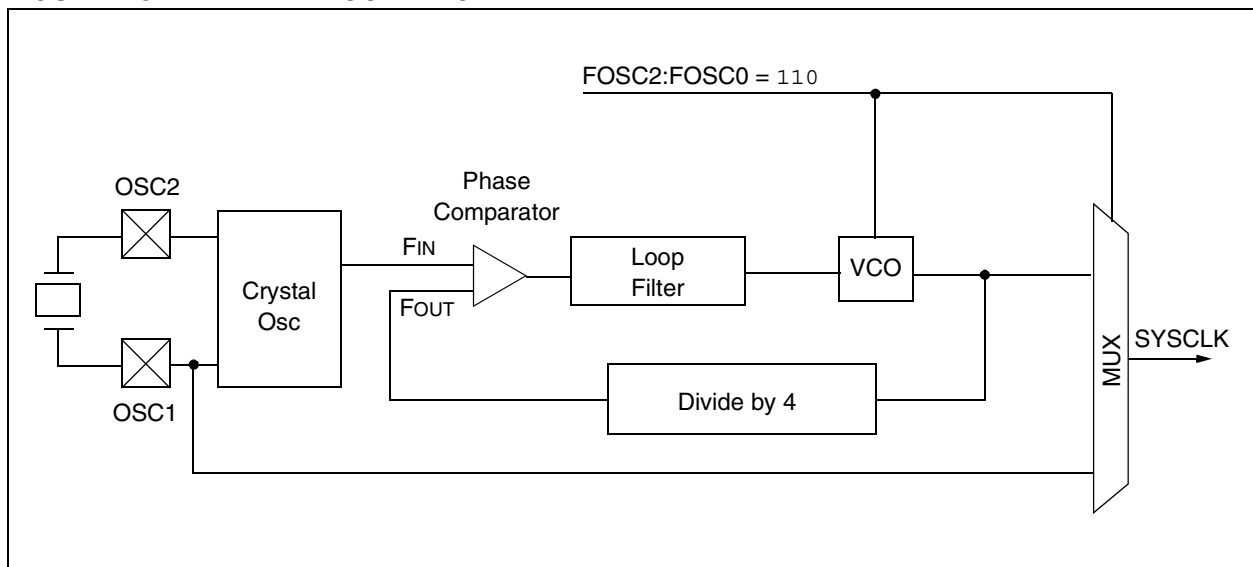
A Phase Locked Loop circuit is provided as a programmable option for users that want to multiply the frequency of the incoming crystal oscillator signal by 4. For an input clock frequency of 10 MHz, the internal clock frequency will be multiplied to 40 MHz. This is useful for customers who are concerned with EMI due to high-frequency crystals.

The PLL can only be enabled when the oscillator configuration bits are programmed for HS mode. If they are programmed for any other mode, the PLL is not enabled and the system clock will come directly from OSC1.

The PLL is one of the modes of the FOSC2:FOSC0 configuration bits. The oscillator mode is specified during device programming.

A PLL lock timer is used to ensure that the PLL has locked before device execution starts. The PLL lock timer has a time-out referred to as TPLL.

**FIGURE 2-5: PLL BLOCK DIAGRAM**





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## 2.6 Oscillator Switching Feature

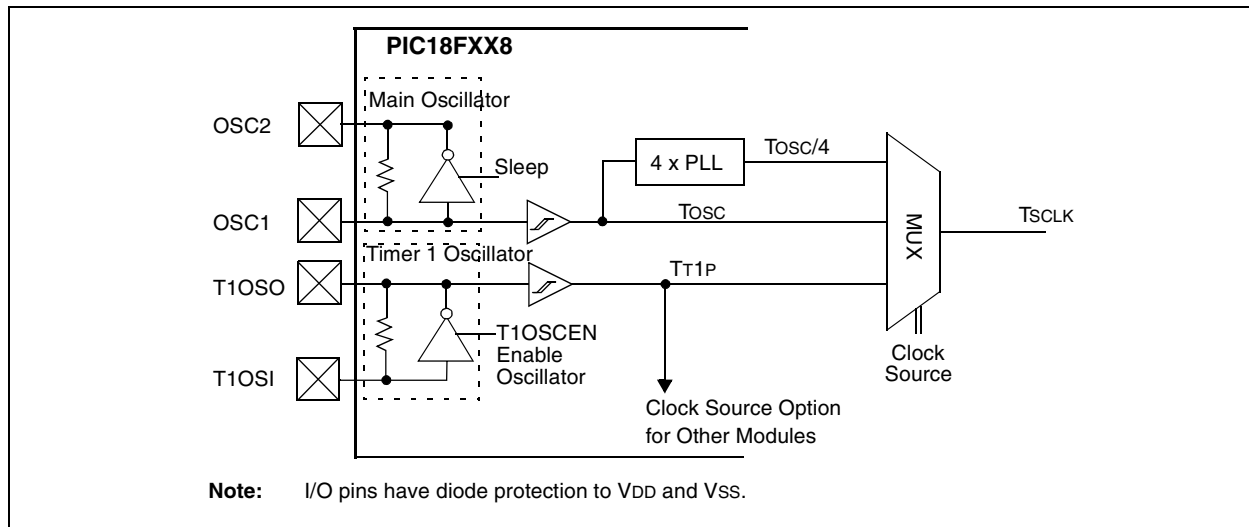
The PIC18FXX8 devices include a feature that allows the system clock source to be switched from the main oscillator to an alternate low-frequency clock source. For the PIC18FXX8 devices, this alternate clock source is the Timer1 oscillator. If a low-frequency crystal (32 kHz, for example) has been attached to the Timer1 oscillator pins and the Timer1 oscillator has been enabled, the device can switch to a Low-Power Execution mode. Figure 2-6 shows a block diagram of the system clock sources. The clock switching feature is enabled by programming the Oscillator Switching Enable ( $\overline{\text{OSCSEN}}$ ) bit in Configuration register, CONFIG1H, to a '0'. Clock switching is disabled in an erased device. See **Section 12.2 "Timer1 Oscillator"** for further details of the Timer1 oscillator and **Section 24.1 "Configuration Bits"** for Configuration register details.

### 2.6.1 SYSTEM CLOCK SWITCH BIT

The system clock source switching is performed under software control. The system clock switch bit, SCS (OSCCON register), controls the clock switching. When the SCS bit is '0', the system clock source comes from the main oscillator selected by the FOSC2:FOSC0 configuration bits. When the SCS bit is set, the system clock source comes from the Timer1 oscillator. The SCS bit is cleared on all forms of Reset.

**Note:** The Timer1 oscillator must be enabled to switch the system clock source. The Timer1 oscillator is enabled by setting the T1OSCEN bit in the Timer1 Control register (T1CON). If the Timer1 oscillator is not enabled, any write to the SCS bit will be ignored (SCS bit forced cleared) and the main oscillator continues to be the system clock source.

**FIGURE 2-6: DEVICE CLOCK SOURCES**



**REGISTER 2-1: OSCCON: OSCILLATOR CONTROL REGISTER**

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-1
—	—	—	—	—	—	—	SCS
bit 7							bit 0

bit 7-1 **Unimplemented:** Read as '0'

bit 0 **SCS:** System Clock Switch bit

When  $\overline{\text{OSCSEN}}$  configuration bit = 0 and T1OSCEN bit is set:

1 = Switch to Timer1 oscillator/clock pin

0 = Use primary oscillator/clock input pin

When  $\overline{\text{OSCSEN}}$  is clear or T1OSCEN is clear:

Bit is forced clear.

**Legend:**

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

## 2.6.2 OSCILLATOR TRANSITIONS

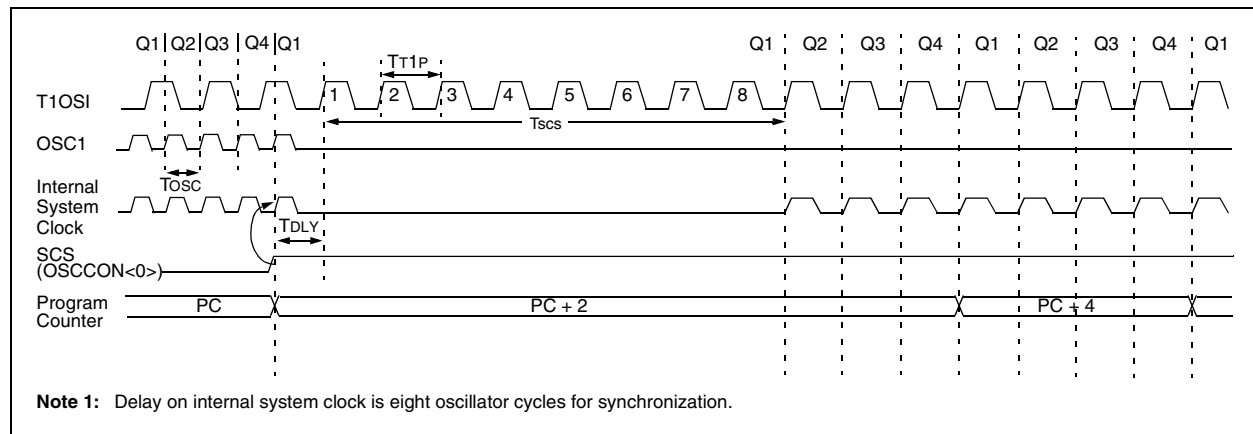
The PIC18FXX8 devices contain circuitry to prevent “glitches” when switching between oscillator sources. Essentially, the circuitry waits for eight rising edges of the clock source that the processor is switching to. This ensures that the new clock source is stable and that its pulse width will not be less than the shortest pulse width of the two clock sources.

Figure 2-7 shows a timing diagram indicating the transition from the main oscillator to the Timer1 oscillator. The Timer1 oscillator is assumed to be running all the time. After the SCS bit is set, the processor is frozen at the next occurring Q1 cycle. After eight synchronization cycles are counted from the Timer1 oscillator, operation resumes. No additional delays are required after the synchronization cycles.

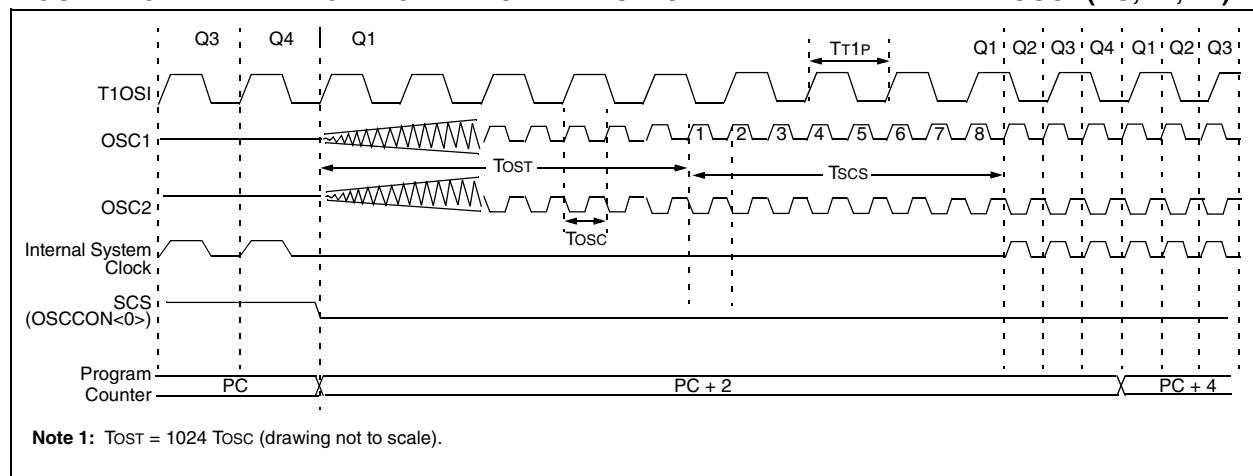
The sequence of events that takes place when switching from the Timer1 oscillator to the main oscillator will depend on the mode of the main oscillator. In addition to eight clock cycles of the main oscillator, additional delays may take place.

If the main oscillator is configured for an external crystal (HS, XT, LP), the transition will take place after an oscillator start-up time ( $T_{OST}$ ) has occurred. A timing diagram indicating the transition from the Timer1 oscillator to the main oscillator for HS, XT and LP modes is shown in Figure 2-8.

**FIGURE 2-7: TIMING DIAGRAM FOR TRANSITION FROM OSC1 TO TIMER1 OSCILLATOR**



**FIGURE 2-8: TIMING DIAGRAM FOR TRANSITION BETWEEN TIMER1 AND OSC1 (HS, XT, LP)**

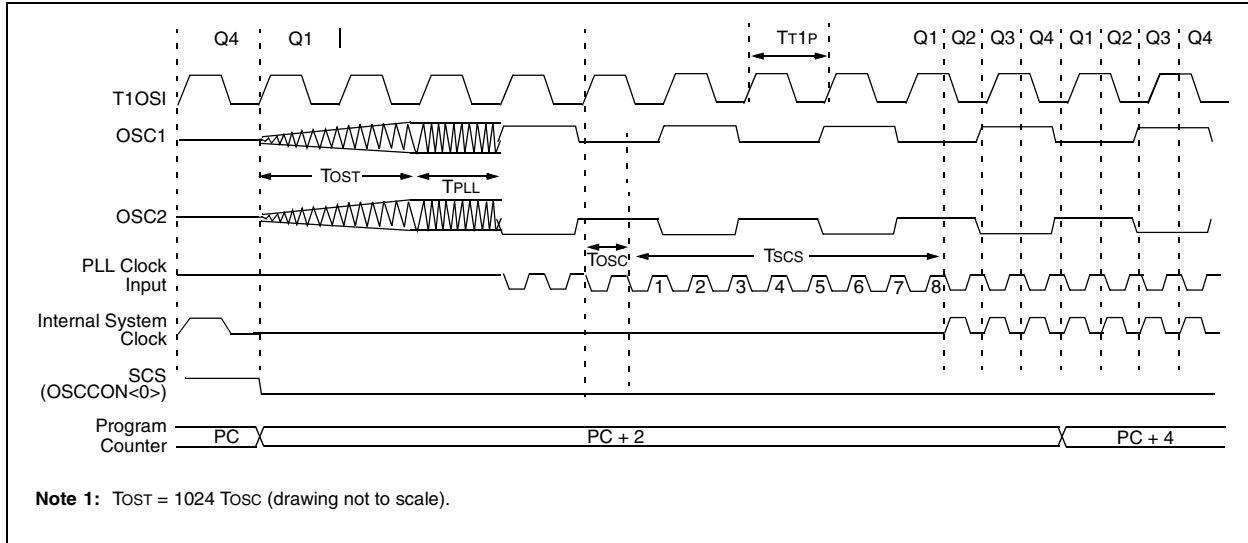


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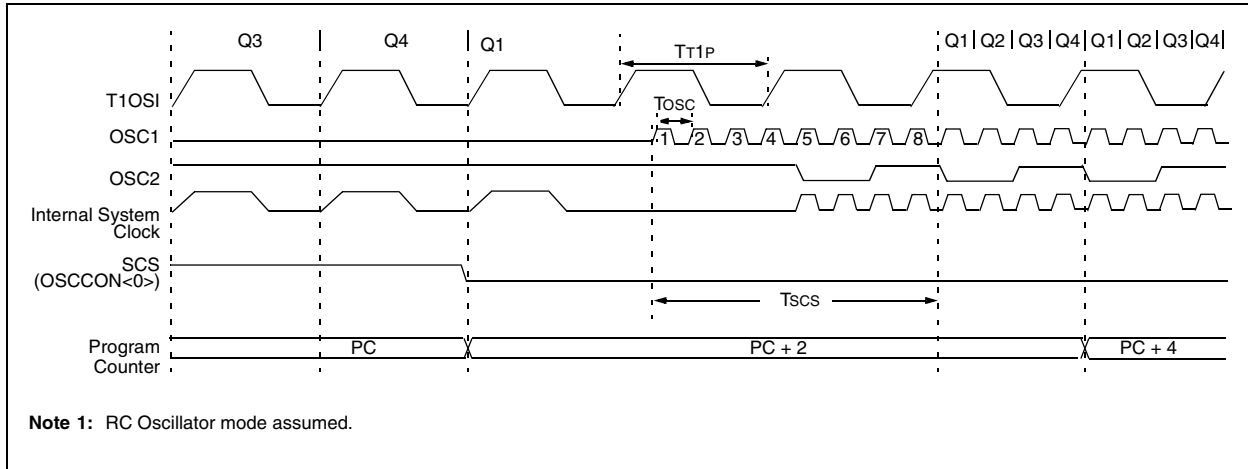
If the main oscillator is configured for HS4 (PLL) mode, an oscillator start-up time ( $T_{OST}$ ) plus an additional PLL time-out ( $T_{PLL}$ ) will occur. The PLL time-out is typically 2 ms and allows the PLL to lock to the main oscillator frequency. A timing diagram indicating the transition from the Timer1 oscillator to the main oscillator for HS4 mode is shown in Figure 2-9.

If the main oscillator is configured in the RC, RCIO, EC or ECIO modes, there is no oscillator start-up time-out. Operation will resume after eight cycles of the main oscillator have been counted. A timing diagram indicating the transition from the Timer1 oscillator to the main oscillator for RC, RCIO, EC and ECIO modes is shown in Figure 2-10.

**FIGURE 2-9: TIMING FOR TRANSITION BETWEEN TIMER1 AND OSC1 (HS WITH PLL)**



**FIGURE 2-10: TIMING FOR TRANSITION BETWEEN TIMER1 AND OSC1 (RC, EC)**



## 2.7 Effects of Sleep Mode on the On-Chip Oscillator

When the device executes a `SLEEP` instruction, the on-chip clocks and oscillator are turned off and the device is held at the beginning of an instruction cycle (Q1 state). With the oscillator off, the OSC1 and OSC2 signals will stop oscillating. Since all the transistor switching currents have been removed, Sleep mode achieves the lowest current consumption of the device (only leakage currents). Enabling any on-chip feature that will operate during Sleep will increase the current consumed during Sleep. The user can wake from Sleep through external Reset, Watchdog Timer Reset or through an interrupt.

## 2.8 Power-up Delays

Power-up delays are controlled by two timers so that no external Reset circuitry is required for most applications. The delays ensure that the device is kept in

Reset until the device power supply and clock are stable. For additional information on Reset operation, see **Section 3.0 “Reset”**.

The first timer is the Power-up Timer (PWRT), which optionally provides a fixed delay of  $T_{PWRT}$  (parameter #D033) on power-up only (POR and BOR). The second timer is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable.

With the PLL enabled (HS4 Oscillator mode), the time-out sequence following a Power-on Reset is different from other oscillator modes. The time-out sequence is as follows: the PWRT time-out is invoked after a POR time delay has expired, then the Oscillator Start-up Timer (OST) is invoked. However, this is still not a sufficient amount of time to allow the PLL to lock at high frequencies. The PWRT timer is used to provide an additional fixed 2 ms (nominal) to allow the PLL ample time to lock to the incoming clock frequency.

**TABLE 2-3: OSC1 AND OSC2 PIN STATES IN SLEEP MODE**

OSC Mode	OSC1 Pin	OSC2 Pin
RC	Floating, external resistor should pull high	At logic low
RCIO	Floating, external resistor should pull high	Configured as PORTA, bit 6
ECIO	Floating	Configured as PORTA, bit 6
EC	Floating	At logic low
LP, XT and HS	Feedback inverter disabled at quiescent voltage level	Feedback inverter disabled at quiescent voltage level

**Note:** See Table 3-1 in **Section 3.0 “Reset”** for time-outs due to Sleep and MCLR Reset.